

承認書 Specification For Approval

Customer	·· (客戶)					
Descriptio	n:(產品描述) ——	SMDLED1608				
Part numbe	er:(產品型號)	TJ-S1608B06YJY-A3				
Date:	(日期)					
Approved B	y :(客戶承認)					
Prepared By	· (我司承認)					
	Approval	Check	Design	Sales		
	核准	審核	製作	業務		

Customer Service Hotline: 400-676-8616

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E-MIAL: dg@togialed.com WEB: www.togialed.com



Features

1.6mm × 0.8mm SMT LED, 0.6mm thickness

Low power consumption

Wide view angle

Package: 4000pcs/reel

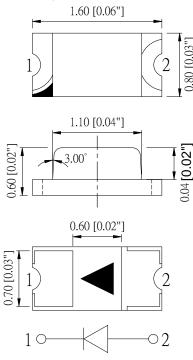
RoHS Compliant

Applications

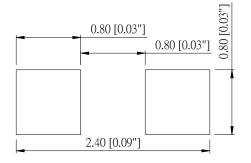
Ideal for back light and indicator

Various colors and lens types available

Package outlines



Recommend Pad Layout





Part No.	Emitted color	Dice	Lens color
TJ-S1608B06YJY-A3	Blue	AlGalnP	Water transparent

Notes:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ± 0.1 mm (0.004inch) unless otherwise noted.



TAIWAN TONGJIA OPTOELECTRONICS TECHNOLOGY CO., LTD

Absolute maximum ratings (TA=25 $^{\circ}$ C)

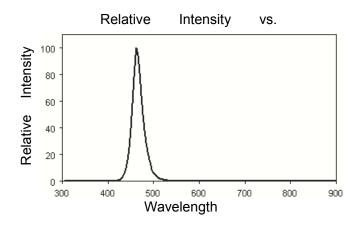
Parameter	Symbol	Value	Unit
Forward current	If	30	mA
Reverse voltage	Vr	5	V
Power dissipation	Pd	72	mW
Operating temperature	Тор	-40 ~+80	$^{\circ}$
Storage temperature	Tstg	-40 ~+85	$^{\circ}$ C
Peak pulsing current (1/8 duty f=1kHz)	Ifp	125	mA

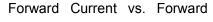
Electro-optical characteristics (TA=25°C)

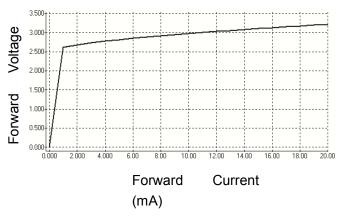
Parameter	Test Condition	Symbol	Value			Unit
Farameter			Min	Тур	Max	Offic
Wavelength at peak emission	If=20mA	λр		465		nm
Spectral half bandwidth	lf=20mA	Δλ		23		nm
Dominant wavelength	lf=20mA	λd	460		470	nm
Forward voltage	If=20mA	Vf	2.8		3.4	V
Luminous intensity	lf=20mA	lv	80		200	mcd
Viewing angle at 50% lv	If=10mA	2 θ 1/2		120		Deg
Reverse current	Vr=5V	lr			10	μΑ



Optical characteristic curves

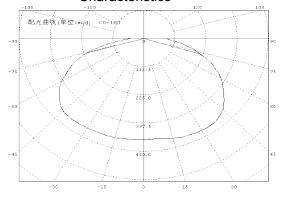






Directive

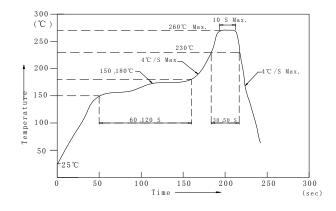
Characteristics





Reflow Profile

■ Reflow Temp/Time



Notes:

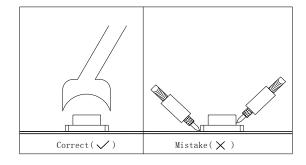
- 1.We recommend the reflow temperature $245^{\circ}\text{C}(\pm 5^{\circ}\text{C})$.the maximum soldering temperature should be limited to 260°C .
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is \leq 5sec when 260 °C. If temperature is higher, time should be shorter (+10 °C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230 °C.

■Rework

- 1.Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.

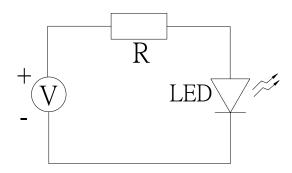


■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.



Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5° C ~ 30° C (41° F ~ 86° F)

2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. after the package is Opened, the products should be used within a week or they should be keeping to stored at ≤20 R.H. with zip-lock sealed.</p>

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

3.1 60 ± 3 °C x(12~24hrs) and <5%RH, taped reel type

3.2 $100\pm3^{\circ}$ C x(45min~1hr), bulk type

3.3 130 \pm 3°C x(15~30min), bulk type



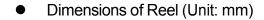
Test items and results of reliability

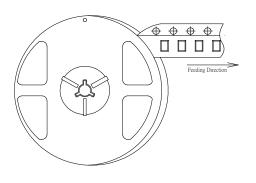
Туре	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Temperature Cycle	-20℃ 30min ↑↓ 80℃ 30min	100 cycle	0/22
	Thermal Shock	-20℃ 15min ↑↓ 80℃ 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C⇔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	Ta=80°C	1000 hrs	0/22
	Humidity Heat Storage	Ta=60℃ RH=90%	1000 hrs	0/22
	Low Temperature Storage	Ta=-30°C	1000 hrs	0/22
Operation Sequence	Life Test	Ta=25℃ IF=20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60℃ RH=90% IF=10mA	500 hrs	0/22
	Low Temperature Life Test	Ta=-20℃ IF=20mA	1000 hrs	0/22

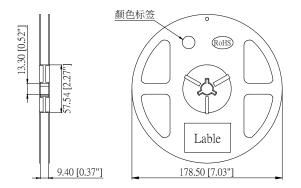


1608 Series SMD Chip LED Lamps Packaging Specifications

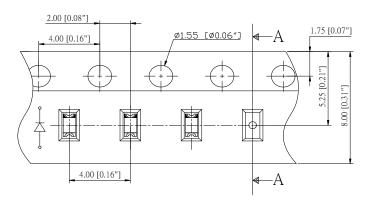
Feeding Direction

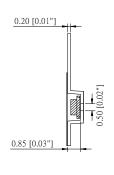




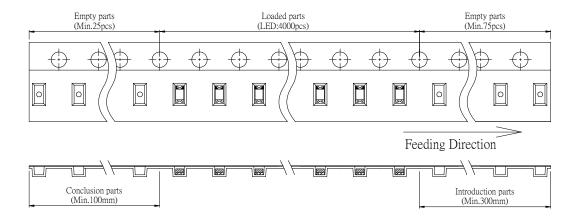


Dimensions of Tape (Unit: mm)





Arrangement of Tape



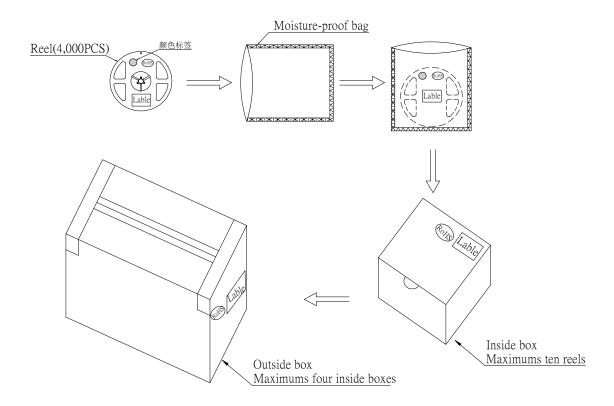
Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
- 4. 4,000 pcs/Reel.



1608 Series SMD Chip LED Lamps Packaging Specifications

Packaging specifications



Notes:

Reeled products (numbers of products are 4,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, ten moisture-proof bag of maximums (total maximum number of products are 40,000pcs) packed in an inside box (about size: 240x 220x 120mm) and four inside boxes of maximums are put in the outside box (about size: 460mm x 246mm x 250mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has it to three steps.